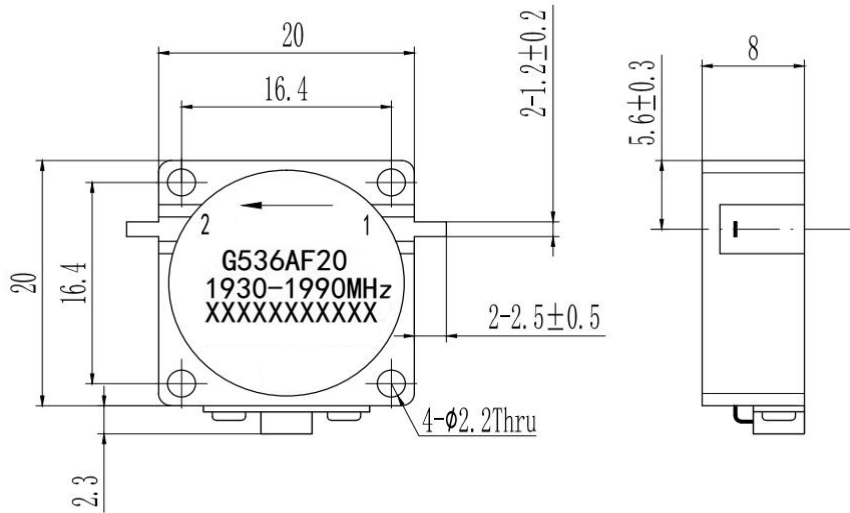


1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions



3.Specifications

Part No.	Frequency (GHz)		Center Frequency (GHz)	Bandwidth (GHz)	Isolation (dB) MIN	INS LOSS (dB) MAX	VSWR (dB) MAX	Power (W)	IMD (@2X43dBm) (-dBc) MAX
	F1	F2							
G536A [820-835]MHz	0.820	0.835	0.828	0.015	23	0.3	1.15	150	
G536A [832-860]MHz	0.832	0.860	0.846	0.028	23	0.3	1.15	60	
G536A [840-845]MHz	0.840	0.845	0.843	0.005	23	0.3	1.15	60	
G536A [885-915]MHz	0.885	0.915	0.900	0.030	23	0.3	1.15	60	
G536A [869-894]MHz	0.869	0.894	0.8815	0.025	25	0.3	1.15	100	
G536A [920-925]MHz	0.920	0.925	0.9225	0.005	23	0.3	1.15	60	
G536A [1710-1785]MHz	1.710	1.785	1.7475	0.075	23	0.25	1.15	60	
G536A [1805-1880]MHz	1.805	1.880	1.8375	0.075	25	0.25	1.15	60	
G536A [1920-1980]MHz	1.920	1.980	1.9500	0.060	23	0.25	1.15	60	
G536A [1930-1990]MHz	1.930	1.990	1.9600	0.060	23	0.25	1.15	60	
G536A [2000-2500]MHz	2.000	2.500	2.2500	0.500	18	0.35	1.28	100	
G536A [2110-2170]MHz	2.110	2.170	2.1400	0.060	25	0.25	1.15	60	
G536A [2200-2300]MHz	2.200	2.300	2.2500	0.100	23	0.25	1.15	60	
G536A [2320-2370]MHz	2.320	2.370	2.3450	0.050	23	0.25	1.15	60	
G536A [2500-2570]MHz	2.500	2.570	2.5350	0.070	23	0.25	1.15	60	
G536A [2570-2690]MHz	2.570	2.690	2.6300	0.120	22	0.25	1.17	60	